

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Patent Application of:
Masahiko FURUNO et al.

Application No.: 10/771,990

Confirmation No.: 3571

Filed: February 3, 2004

Art Unit: 1725

For: BUMP FORMING METHOD,
PRESOLDERING TREATMENT METHOD,
SOLDERING METHOD, BUMP FORMING
APPARATUS, PRESOLDERING
TREATMENT DEVICE AND SOLDERING
APPARATUS

Examiner: Michael Aboagye

RESPONSE TO NON-FINAL OFFICE ACTION

MS Amendment
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Dear Sir:

INTRODUCTORY COMMENTS

In response to the non-final Office Action dated December 29, 2006, please amend the above-identified U.S. patent application as follows:

Amendments to the Claims are reflected in the listing of claims which begins on page 2 of this paper.

Remarks/Arguments begin on page 9 of this paper.